



DCR490J65

Phase Control Thyristor

Replaces DS5930-2 DS5830-3 June 2014 (LN31677)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

| Part and Ordering Number | Repetitive Peak Voltages V _{DRM} and V _{RRM} V | Conditions |
|--------------------------------------|---|---|
| DCR490J65* DCR490J60 DCR490J55 | 6500 6000 5500 | $\begin{split} T_{\nu j} &= \text{-}40 ^{\circ}\text{C to 125} ^{\circ}\text{C}, \\ I_{DRM} &= I_{RRM} = 100 \text{mA}, \\ V_{DRM}, V_{RRM} t_p &= 10 \text{ms}, \\ V_{DSM} \& V_{RSM} &= \\ V_{DRM} \& V_{RRM} + 100 V \\ respectively \end{split}$ |

Lower voltage grades available. *6200V @ -40° C, 6500V @ 0° C

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR490J65

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

 $\begin{array}{lll} V_{DRM} & 6500V \\ I_{T(AV)} & 490A \\ I_{TSM} & 6600A \\ dV/dt^* & 1500V/\mu s \\ dI/dt & 200A/us \end{array}$

* Higher dV/dt selections available

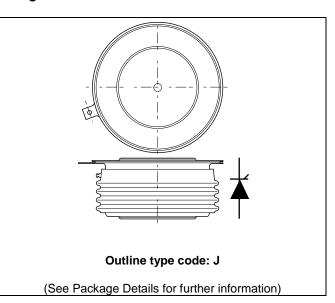


Fig. 1 Package outline

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CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

| Symbol | Parameter | Test Conditions | Max. | Units |
|---------------------|--------------------------------------|--------------------------|------|-------|
| Double Si | de Cooled | | | |
| I _{T(AV)} | Mean on-state current | Half wave resistive load | 490 | А |
| I _{T(RMS)} | RMS value | - | | Α |
| Ι _Τ | Continuous (direct) on-state current | - | 730 | Α |

SURGE RATINGS

| Symbol Parameter | | Test Conditions | Max. | Units |
|------------------|---|---|------|-------------------|
| I _{TSM} | Surge (non-repetitive) on-state current | 10ms half sine, T _{case} = 125°C | 6.6 | kA |
| l ² t | I ² t for fusing | $V_R = 0$ | 0.22 | MA ² s |

THERMAL AND MECHANICAL RATINGS

| Symbol | Parameter | Test Conditions | | Min. | Max. | Units |
|----------------------|---------------------------------------|---|-------------|------|--------|-------|
| R _{th(j-c)} | Thermal resistance – junction to case | Double side cooled | DC | - | 0.0379 | °C/W |
| | | Single side cooled | Anode DC | - | 0.0745 | °C/W |
| | | | Cathode DC | - | 0.0797 | °C/W |
| R _{th(c-h)} | Thermal resistance – case to heatsink | Clamping force 11.5kN Double side | | - | 0.0072 | °C/W |
| | | (with mounting compound) | Single side | - | .0144 | °C/W |
| T _{vj} | Virtual junction temperature | Blocking V _{DRM} / _{VRRM} | | - | 125 | °C |
| T _{stg} | Storage temperature range | | | -55 | 125 | °C |
| F _m | Clamping force | | | 10 | 13 | kN |

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DYNAMIC CHARACTERISTICS

| Symbol | Parameter | Test Conditions | | Min. | Max. | Units |
|------------------------------------|---|--|-------------------------|------|-------|-------|
| I _{RRM} /I _{DRM} | Peak reverse and off-state current | At V _{RRM} /V _{DRM} , T _{case} = 125°C | | - | 100 | mA |
| dV/dt | Max. linear rate of rise of off-state voltage | To 67% V _{DRM} , T _j = 125°C, ga | ate open | - | 1500 | V/µs |
| dl/dt | Rate of rise of on-state current | From 67% V _{DRM} to 2x I _{T(AV)} | Repetitive 50Hz | - | 100 | A/µs |
| | | Gate source 30V, 10Ω, | Non-repetitive | - | 200 | A/µs |
| | | $t_r < 0.5 \mu s, T_j = 125 ^{\circ} C$ | | | | |
| V _{T(TO)} | Threshold voltage – Low level | 50A to 400A at T _{case} = 125°C | ; | - | 0.912 | V |
| | Threshold voltage – High level | 400A to 1600A at T _{case} = 125°C | | - | 1.108 | V |
| r _T | On-state slope resistance – Low level | 50A to 400A at T _{case} = 125°C | | - | 2.157 | mΩ |
| | On-state slope resistance – High level | 400A to 1600A at T _{case} = 125°C | | - | 1.647 | mΩ |
| t _{gd} | Delay time | $V_D = 67\% V_{DRM}$, gate source 30V, 10Ω | | - | 3 | μs |
| | | $t_r = 0.5 \mu s, T_j = 25^{\circ}C$ | | | | |
| t _q | Turn-off time | IT = 500A,T _j = 125°C, V _R = 100V, dl/dt = 5A/µs, | | 550 | 1100 | μs |
| | | dV _{DR} /dt = 20V/μs linear | | | | |
| Q _S | Stored charge | $I_T = 500A$, $T_j = 125$ °C, $dI/dt = 5A/\mu s$, | | 1800 | 2600 | μC |
| I _{RR} | Reverse recovery current | $I_T = 500A$, $T_j = 125$ °C, $dI/dt = 5A/\mu s$, | | 77 | 90 | Α |
| IL | Latching current | $T_j = 25^{\circ}C, V_D = 5V$ | | - | 3 | А |
| I _H | Holding current | $T_j = 25^{\circ}\text{C}, R_{G-K} = \infty, I_{TM} = 500$ | 0A, I _T = 5A | - | 300 | mA |

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GATE TRIGGER CHARACTERISTICS AND RATINGS

| Symbol | Parameter | Parameter Test Conditions | | Units |
|-----------------|--------------------------|---|-----|-------|
| V_{GT} | Gate trigger voltage | $V_{DRM} = 5V$, $T_{case} = 25$ °C | 1.5 | V |
| V_{GD} | Gate non-trigger voltage | At 50% V _{DRM} , T _{case} = 125°C | 0.4 | V |
| I _{GT} | Gate trigger current | $V_{DRM} = 5V$, $T_{case} = 25$ °C | 350 | mA |
| I _{GD} | Gate non-trigger current | At 50% V _{DRM} , T _{case} = 125°C | 15 | mA |

CURVES

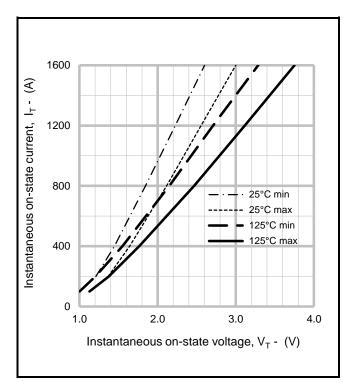


Fig.2 Maximum & minimum on-state characteristics

 $\begin{array}{lll} \textbf{V}_{\text{TM}} \; \textbf{EQUATION} & \text{Where} & A = 0.542452 \\ B = 0.065613 \\ V_{\text{TM}} = A + B \text{ln} \; (I_{\text{T}}) + C.I_{\text{T}} + D.\sqrt{I_{\text{T}}} & C = 0.001318 \\ D = 0.015356 \end{array}$

these values are valid for $T_j = 125^{\circ}C$ for I_T 50A to 1600A

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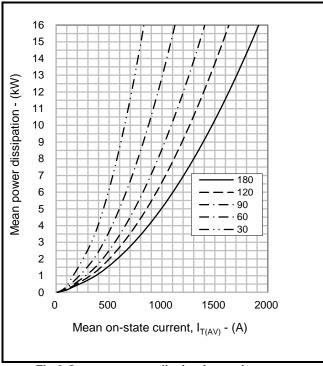


Fig.3 On-state power dissipation - sine wave

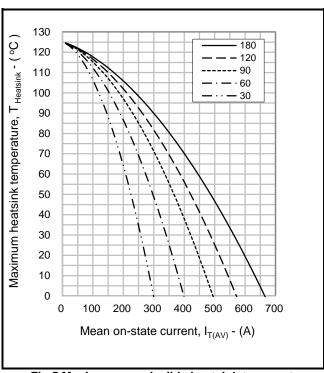


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

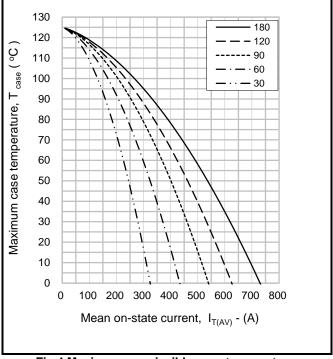


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

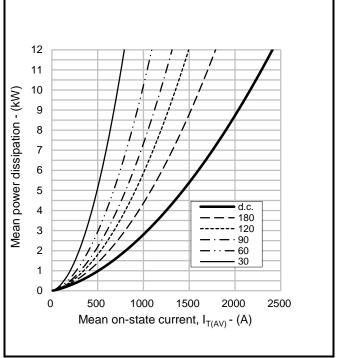


Fig.6 On-state power dissipation - rectangular wave

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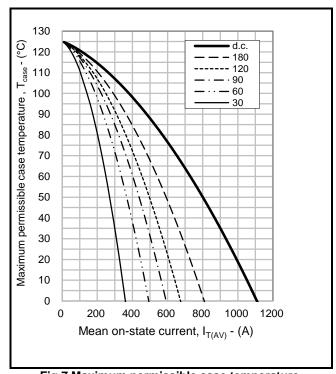


Fig.7 Maximum permissible case temperature, double side cooled - rectangular wave

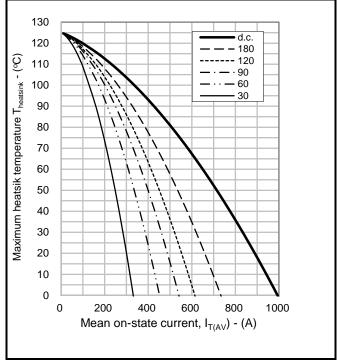
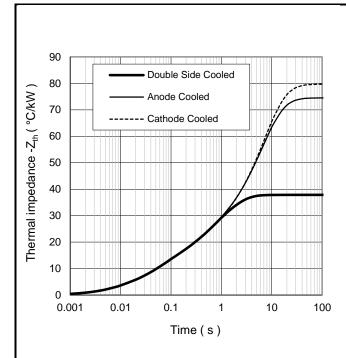


Fig.8 Maximum permissible heatsink temperature, double side cooled - rectangular wave



| | | 1 | 2 | 3 | 4 |
|---------------------|------------------------|-----------|-----------|-----------|---------|
| Double side cooled | R _i (°C/kW) | 2.4256 | 9.3503 | 10.6963 | 15.3758 |
| | T _i (s) | 0.0087759 | 0.053099 | 0.4497246 | 1.395 |
| Anode side cooled | R _i (°C/kW) | 2.8091 | 9.5576 | 11.3564 | 50.6136 |
| | T _i (s) | 0.0097443 | 0.0591913 | 0.4759179 | 6.5548 |
| Cathode side cooled | R _i (°C/kW) | 2.9507 | 9.4031 | 11.0771 | 56.0405 |
| | T _i (s) | 0.0100391 | 0.0606056 | 0.4732916 | 7.228 |

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(-T/T_i))]$$

 $\Delta R_{\text{th(j-c)}}$ Conduction

Tables show the increments of thermal resistance $R_{\text{th(j-c)}}$ when the device operates at conduction angles other than d.c.

| | Double side cooling | | | | | | |
|-----|---------------------|------|--|--|--|--|--|
| | $\Delta Z_{th}(z)$ | | | | | | |
| θ° | sine. rect. | | | | | | |
| 180 | 4.43 | 3.01 | | | | | |
| 120 | 5.13 | 4.30 | | | | | |
| 90 | 5.89 | 5.03 | | | | | |
| 60 | 6.58 | 5.81 | | | | | |
| 30 | 7.12 | 6.67 | | | | | |

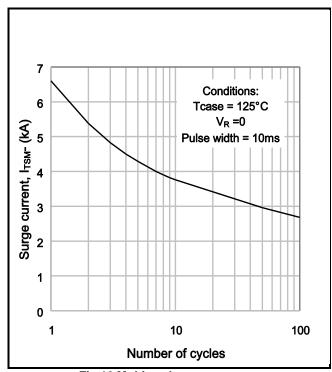
| | Double side cooling | | Anode Side Cooling | | l | Ca | tnode Side | d Cooling | |
|-----|---------------------|-------|---------------------|-------|-------|----|--------------|------------------|-------|
| | ΔZ_{th} | (z) | ΔZ_{th} (z) | | | | ΔZ_t | _h (z) | |
| θ° | sine. | rect. | θ° | sine. | rect. | | θ° | sine. | rect. |
| 180 | 4.43 | 3.01 | 180 | 4.39 | 2.99 | | 180 | 4.37 | 2.98 |
| 120 | 5.13 | 4.30 | 120 | 5.07 | 4.26 | | 120 | 5.05 | 4.25 |
| 90 | 5.89 | 5.03 | 90 | 5.81 | 4.97 | | 90 | 5.79 | 4.96 |
| 60 | 6.58 | 5.81 | 60 | 6.48 | 5.74 | | 60 | 6.45 | 5.72 |
| 30 | 7.12 | 6.67 | 30 | 7.00 | 6.57 | | 30 | 6.97 | 6.54 |
| 15 | 7.36 | 7.13 | 15 | 7.24 | 7.01 | | 15 | 7.20 | 6.98 |

| Sa | Cathode Sided Cooling | | | | | | |
|-----|-----------------------|-------|--|--|--|--|--|
| | $\Delta Z_{th}(z)$ | | | | | | |
| θ° | sine. | rect. | | | | | |
| 180 | 4.37 | 2.98 | | | | | |
| 120 | 5.05 | 4.25 | | | | | |
| 90 | 5.79 | 4.96 | | | | | |
| 60 | 6.45 | 5.72 | | | | | |
| 30 | 6.97 | 6.54 | | | | | |
| 4.5 | | 000 | | | | | |

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)

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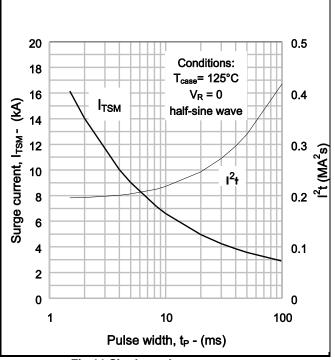


Fig.11 Single-cycle surge current

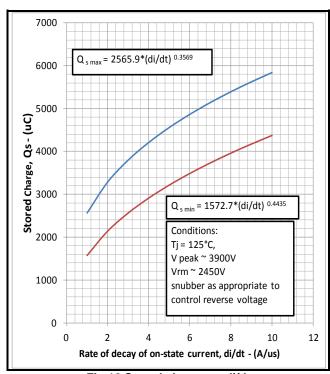


Fig.12 Stored charge vs di/dt

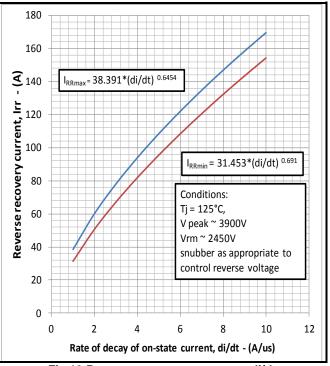


Fig.13 Reverse recovery current vs di/dt

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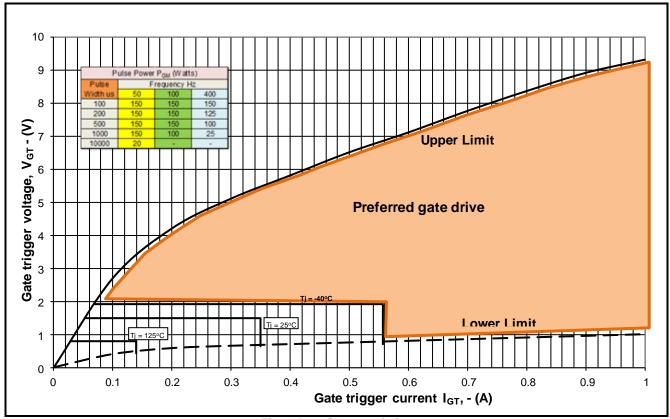


Fig14 Gate Characteristics

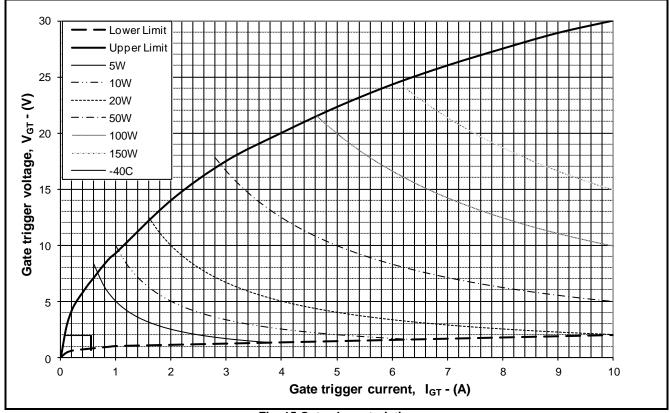


Fig. 15 Gate characteristics

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PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

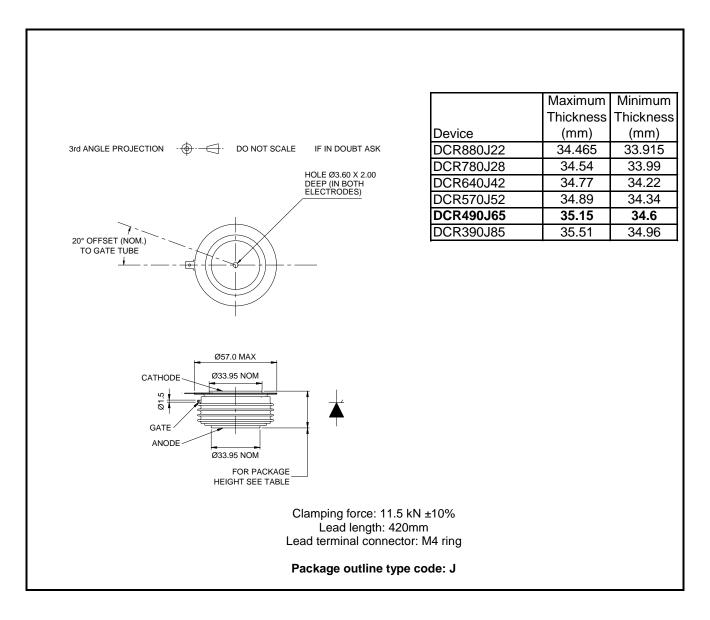


Fig.16 Package outline

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